



E-Song America, Inc.

100%
RoHS Compliant
Products

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THERMAL INTERFACE PAD: THEA770

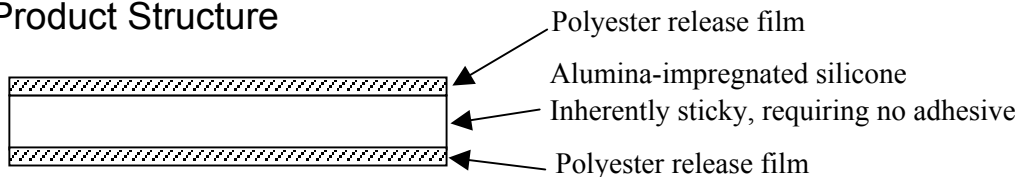
Characteristic

This product is made of conformable, elastic polymer pad filled with Alumina filler providing excellent heat conductivity. It fills air voids between PC boards and heat sink or metal chassis (heat spreader) with high stackup tolerances. Flame retardant UL94V0 and good electrical

Application

- Areas where heat needs to be transferred away to the frame chassis or other type of heat spreader
- Between a CPU and a heat spreader
- Between a CD ROM drive and a heat spreader
- Between a semiconductor and heat sink
- Replacement for messy grease
- Available in custom sizes and die-cut shapes/sizes

Product Structure



Technical data

| ITEM | | VALUE | TEST METHOD | |
|------------------------------------|---------------------------------------|------------------------|-------------------|-------------|
| Material | Binder | Silicone | | |
| | Filler | Alumina | | |
| | Liners (top and bottom) | Polyester | | |
| Mechanical properties | Thickness (mm) | Silicone pad available | 0.5 to 10 ±0.25 | ASTM D 1000 |
| | | Release film | 0.100 | |
| | Standard size (mm) | | 300 x 300 | |
| | Color | Silicone pad | Gray | Visual |
| | | Release film | Transparent | Visual |
| | Hardness (Shore OO) | | 65 ~ 85 | ASTM D 2240 |
| | Specific gravity (g/cm ³) | | 3.5 | ASTM D 792 |
| Continuous usage temp. (°C) | | -60 ~ +180 | | |
| Electrical properties | Dielectric constant | | 3.5 | ASTM D 150 |
| | Dielectric breakdown (kV AC) | | >5 | ASTM D 149 |
| | Volume resistivity (ohm-meter) | | >10 ¹² | ASTM D 257 |
| Thermal conductivity 10psi (w/m.K) | | 7.0 | ASTM D 5470 | |
| Flame Rating | | UL94 V0 | | |

